TOKYO ELECTRON

Q1 FY2027 (April - June 2026) Financial Announcement

July 30, 2026

Agenda:

- Consolidated Financial Summary
  Hiroshi Kawamoto, SVP & GM, CFO, Division Officer of Finance Division
- Business Environment and Financial Estimates
  Toshiki Kawai, Representative Director, President & CEO

Forward Looking Statements

- Disclaimer regarding forward-looking statements
  Forward-looking statements with respect to Tokyo Electron’s business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors, including political and economic situations, semiconductor market conditions, intensification of sales competition, safety and product quality management, intellectual property-related matters and impacts from infectious diseases.

- Processing of numbers
  For the amount listed, because fractions are rounded down, there may be the cases where the total for certain account titles does not correspond to the sum of the respective figures for account titles. Percentages are calculated using full amounts, before rounding.

- Foreign exchange risk
  In principle, export sales of Tokyo Electron’s products is denominated in yen. Although some sales and expenses are denominated in foreign currencies, the impact of foreign exchange rate fluctuations on profits is negligible, unless extreme fluctuations occur.

Q1 FY2027 Consolidated Financial Summary

July 30, 2026

Hiroshi Kawamoto
SVP & GM, CFO, Division Officer of Finance Division

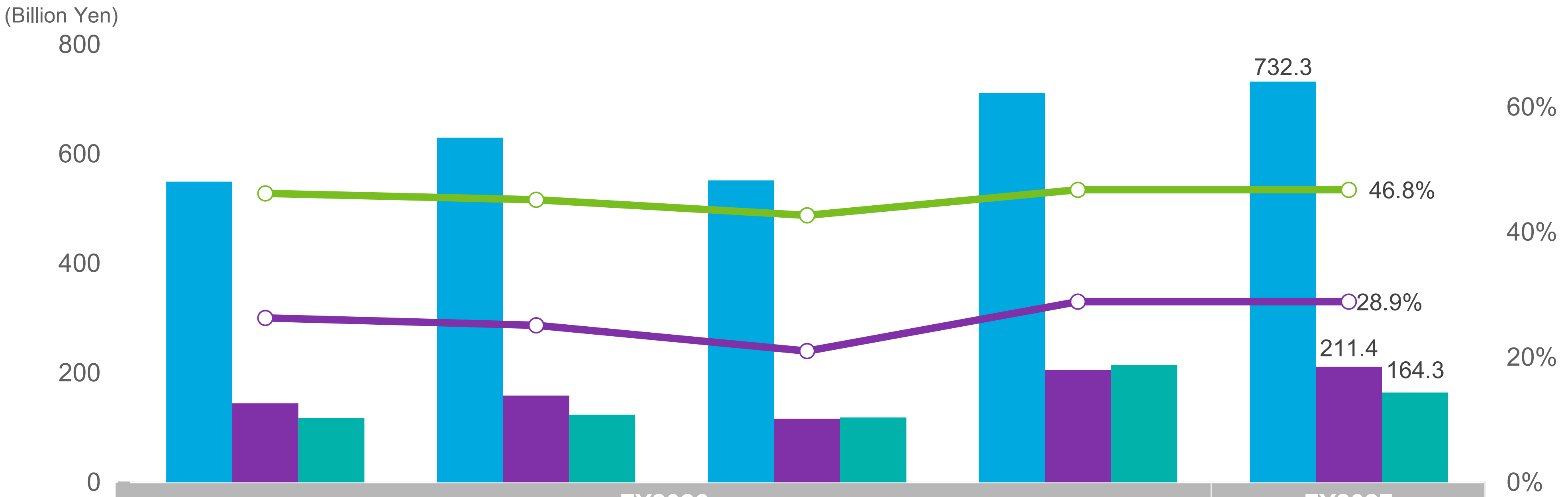
Financial Summary (Quarterly)

(Billion yen)

	FY2026				FY2027	vs. FY2026 Q4	vs. FY2026 Q1
	Q1	Q2	Q3	Q4	Q1		
Net sales	549.5	630.0	552.0	711.8	**732.3**	+2.9%	+33.3%
Gross profit	253.9	284.8	235.8	333.1	**342.7**	+2.9%	+34.9%
Gross profit margin	46.2%	45.2%	42.7%	46.8%	**46.8%**	±0.0pts	+0.6pts
SG&A expenses	109.2	126.4	119.6	127.5	**131.3**	+2.9%	+20.2%
Operating income	144.6	158.4	116.1	205.6	**211.4**	+2.8%	+46.1%
Operating margin	26.3%	25.1%	21.0%	28.9%	**28.9%**	±0.0pts	+2.6pts
Income before income taxes	151.9	161.0	153.3	281.8	**215.4**	-23.5%	+41.8%
Net income attributable to owners of parent	117.8	123.8	118.5	214.2	**164.3**	-23.3%	+39.5%
R&D expenses	62.1	72.6	66.2	76.7	72.0	-6.2%	+15.9%
Capital expenditures	52.8	91.2	30.3	41.6	39.9	-4.1%	-24.4%
Depreciation and amortization	17.1	19.1	21.1	23.5	22.5	-4.4%	+31.2%

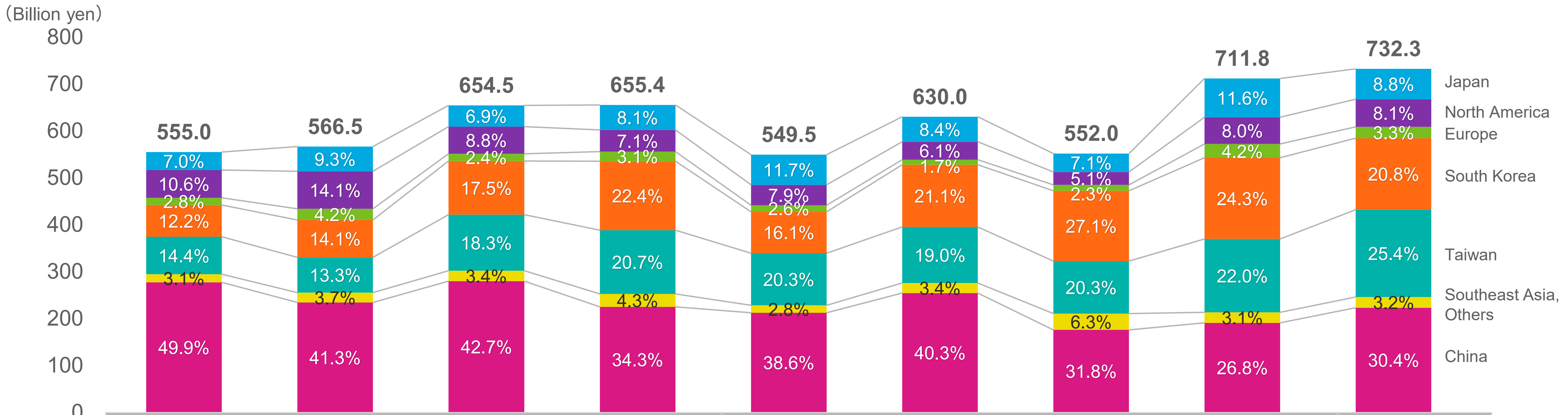
1. In principle, export sales of Tokyo Electron's products are denominated in yen. Although some sales and expenses are denominated in foreign currencies, the impact of foreign exchange rate fluctuations on profits is negligible, unless extreme fluctuations occur.
2. Profit ratios are calculated using full amounts, before rounding.
3. FY20xx refers to the financial year ending in March 20xx.

Financial Performance (Quarterly)



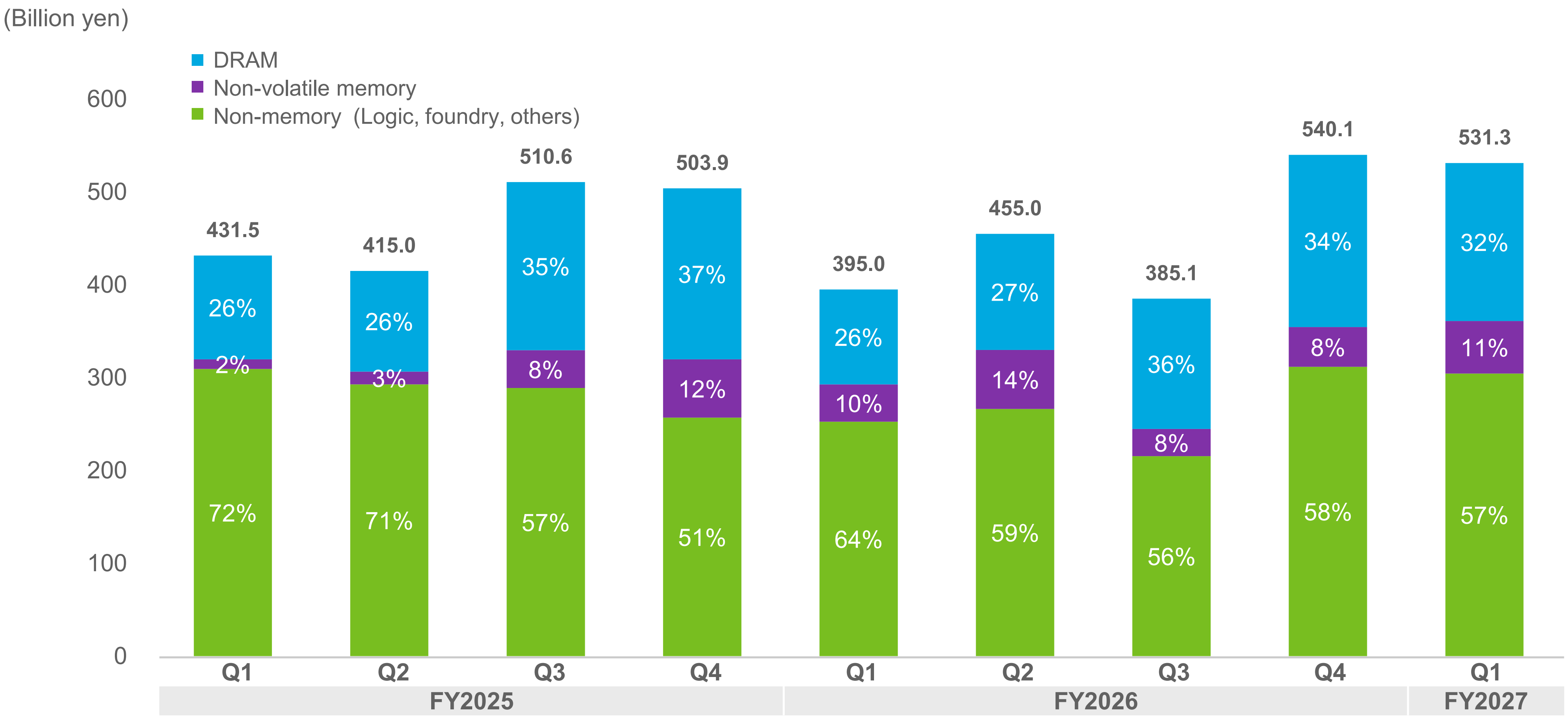
	FY2026				FY2027
	Q1	Q2	Q3	Q4	Q1
Net sales	549.5	630.0	552.0	711.8	**732.3**
Gross profit	144.6	158.4	116.1	205.6	**211.4**
Operating profit	117.8	123.8	118.5	214.2	**164.3**
Net income attributable to owners of parent	46.2%	45.2%	42.7%	46.8%	**46.8%**
Gross profit margin	26.3%	25.1%	21.0%	28.9%	**28.9%**

Composition of Net Sales by Region (Quarterly)



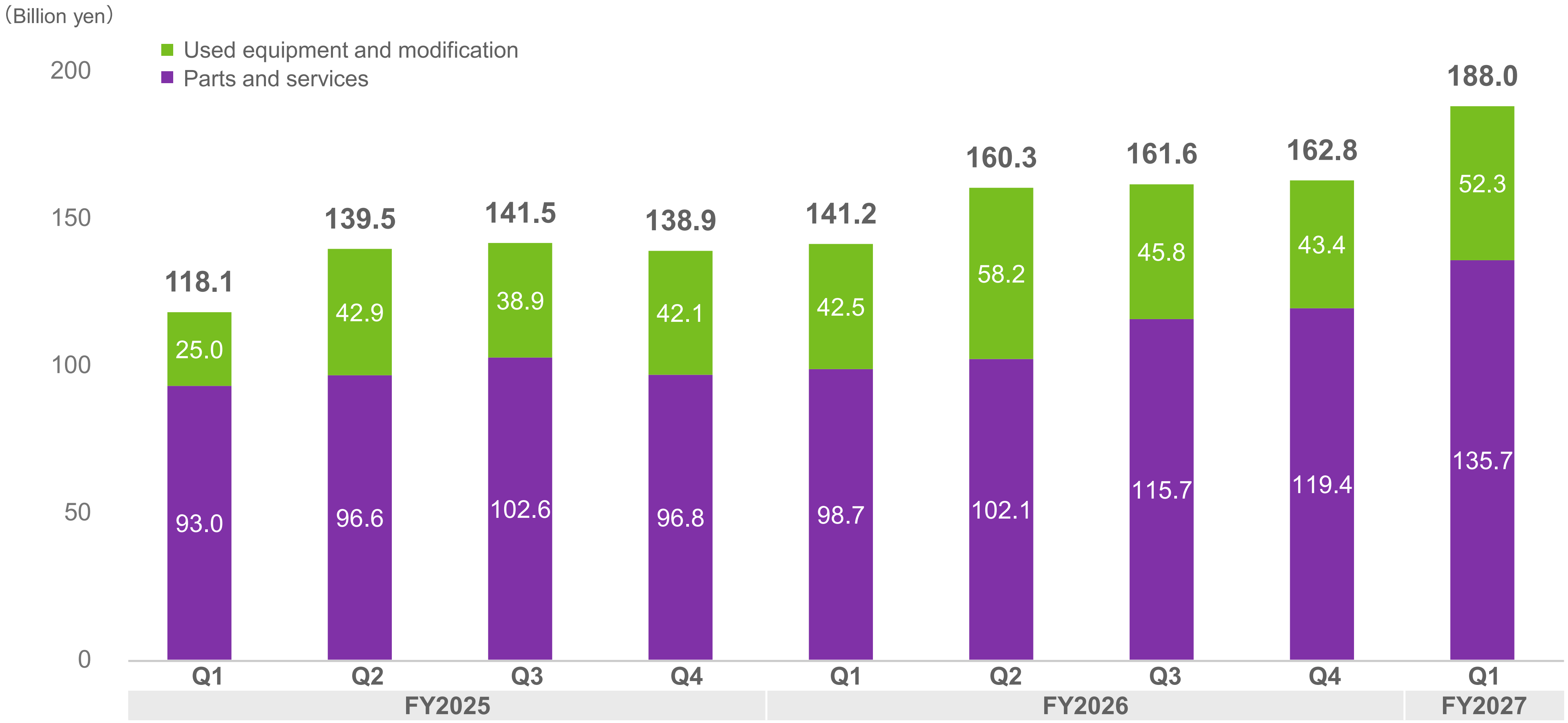
	FY2025				FY2026				FY2027
	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1
Japan	38.5	52.6	45.3	53.4	64.3	52.9	39.3	82.8	**64.6**
North America	59.0	79.9	57.7	46.2	43.4	38.4	27.8	56.7	**59.0**
Europe	15.5	23.8	15.7	20.3	14.0	10.8	12.7	29.7	**24.2**
South Korea	67.8	79.5	114.5	147.0	88.3	132.5	149.7	173.1	**152.4**
Taiwan	80.0	75.3	119.3	135.8	111.5	119.7	111.9	156.5	**186.1**
Southeast Asia, Others	17.0	21.2	22.3	27.8	15.6	21.3	34.8	22.1	**22.9**
China	277.0	233.9	279.4	224.6	212.1	254.1	175.5	190.7	**222.9**

SPE New Equipment Sales by Application (Quarterly)

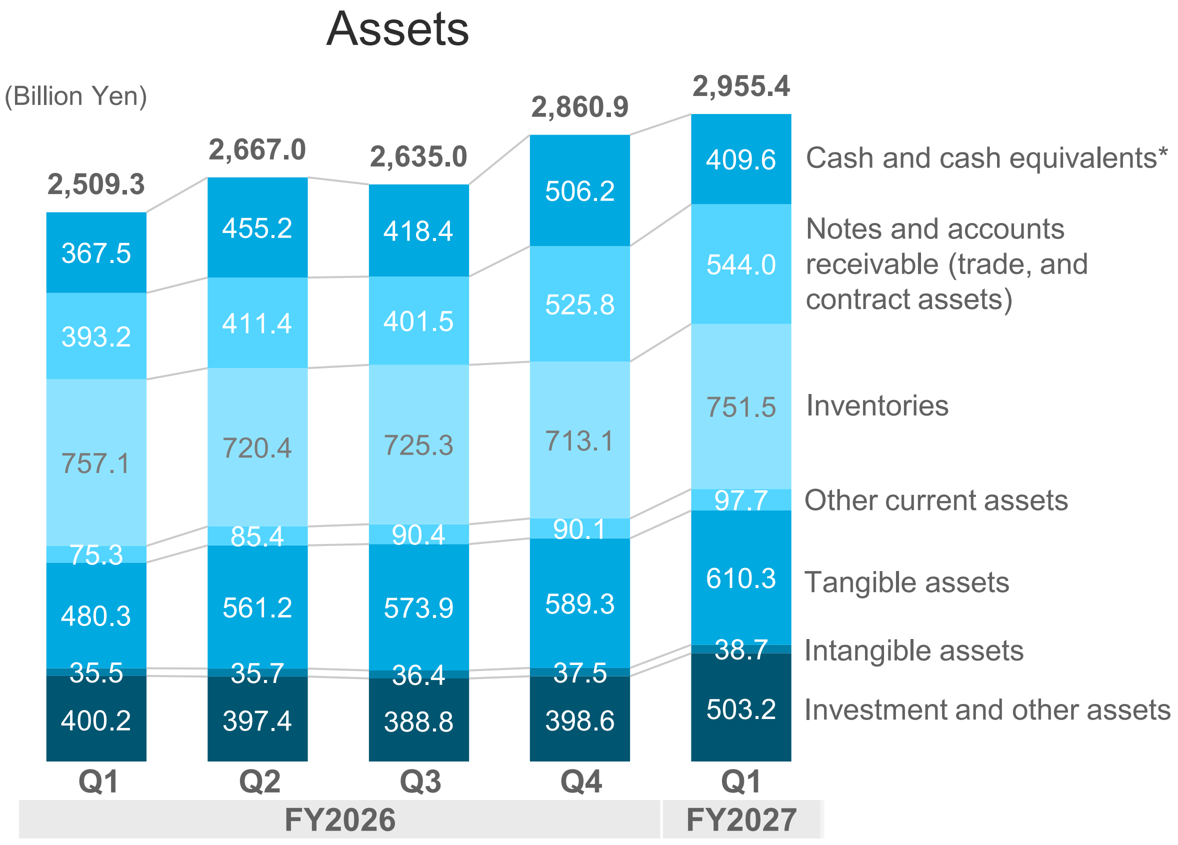


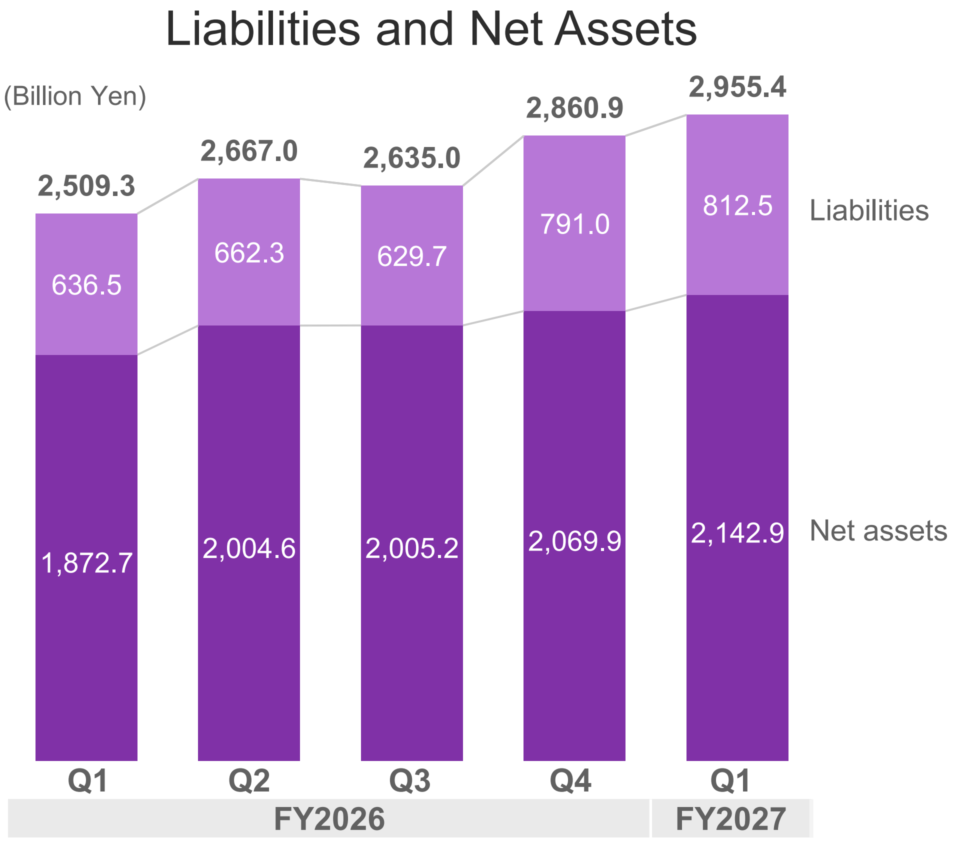
1. SPE: Semiconductor Production Equipment
2. Percentages on the graph show the composition ratio of new equipment sales. Field Solutions sales are not included.

Field Solutions Sales (Quarterly)



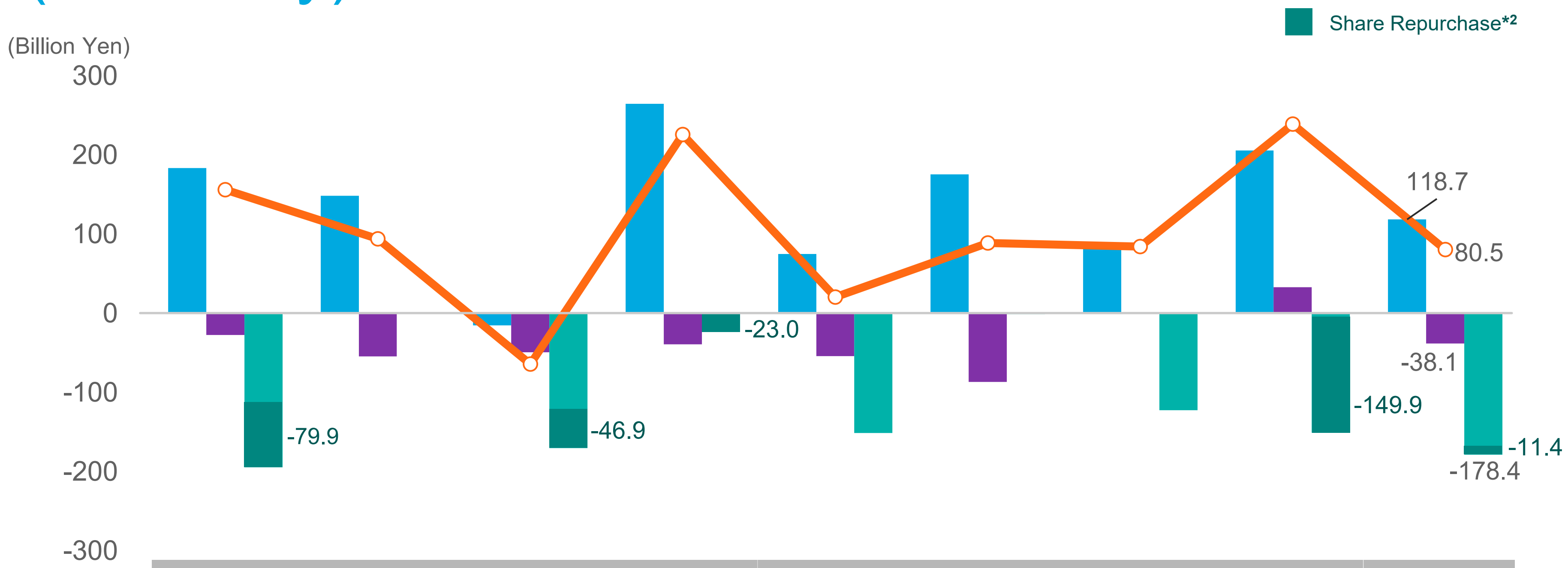
Balance Sheet (Quarterly)





*Cash and cash equivalents: “Cash and deposits” + “Short-term investments”, etc. (“Securities” in Balance Sheet).

Cash Flow (Quarterly)



	FY2025				FY2026				FY2027
	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1
Cash flow from operating activities	183.7	148.6	-15.0	264.8	74.9	175.8	83.1	205.7	**118.7**
Cash flow from investing activities*1	-27.3	-54.4	-49.0	-38.9	-54.1	-86.7	1.2	33.2	**-38.1**
Cash flow from financing activities	-194.4	-0.6	-170.1	-23.5	-151.1	-1.0	-122.3	-150.8	**-178.4**
Free cash flow*3	156.4	94.1	-64.1	225.8	20.7	89.1	84.3	239.0	**80.5**
Cash on hand*4	438.5	525.5	295.5	496.2	367.5	455.2	418.4	506.2	**409.6**

*1 Cash flow from investing activities excludes changes in time deposits and short-term investments.
*2 The amount for share repurchase excludes the cost incurred to purchase odd-lot shares.
*3 Free cash flow = “Cash flow from operating activities” + “Cash flow from investing activities” (excluding changes in “Time deposits” and “Short-term investments”).
*4 Cash on hand includes “Cash and cash equivalents” + “Time deposits and short-term investments” with original maturities of more than three months.

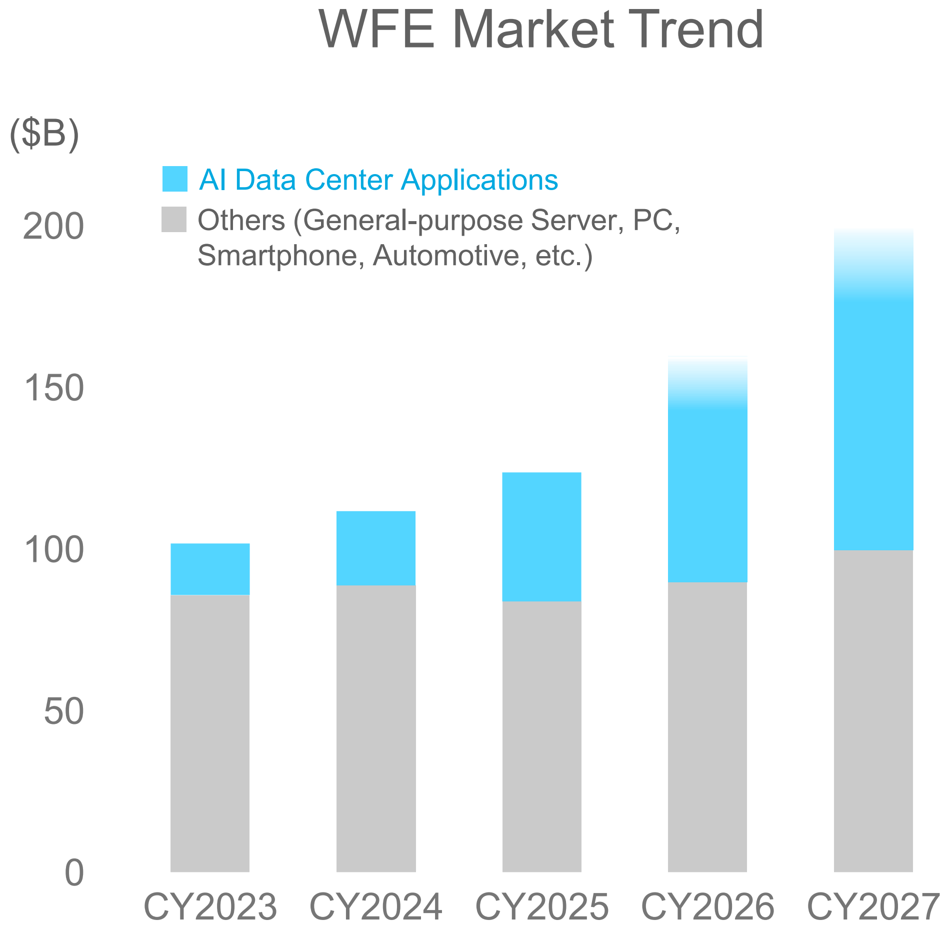
TOKYO ELECTRON

Business Environment and Financial Estimates

July 30, 2026

Toshiki Kawai
Representative Director, President & CEO

Business Environment (WFE Market Outlook as of July 2026)



WFE Market Outlook

- CY2026: $150B+
- CY2027: $190B+
- Demand for general-purpose memory /CPU is increasing as well as for GPU/HBM
- Investment plans for leading-edge chips are accelerating

WFE for AI data centers are growing to exceed 50% of total

With our strong position in advanced areas, our opportunities are expanding even further

Evolution of AI and Semiconductor Technology Trends

	2026 – 2027	2027 – 2028
AI	Generative AI	Agentic AI Physical AI
CPU/GPU	2-3nm	Beyond 2nm + BSPDN*
DRAM/HBM	1c / 12hi	1d / 16hi
NAND	2yy-3xxL	4xxL

Significant technological innovations are happening across devices as AI evolves

* BSPDN (Backside Power Delivery Network) : Structures that arrange power delivery networks on the backside of silicon wafer

Status of Financial Targets for Medium-term Management Plan

Financial Targets (~March 2027)		
Net Sales	**≥ 3 trillion yen**	**On Track**
OPM	**≥ 35%**	**In Progress**
ROE	**≥ 30%**	**On Track**

While achieving our operating profit margin target remains challenging,
steady progress to date is putting operating profit of 1 trillion yen within reach

Initiatives to Improve Profitability

1. Develop next-generation systems with higher added value
2. Drive productivity gains through system upgrades
3. Roll out AI- and robotics-enabled service + Epsira
4. Enhance startup efficiency and reduce startup lead times
5. Pricing optimization

We will strengthen our ability to generate earnings while remaining agile to market changes

FY2027 Update: Progress and Business Opportunities Ahead

Business Progress
(FY2027 Sales Growth Drivers)

Coater/ Developer	Sales Growth 50%+ YoY	▪ Newly released CLEAN TRACK™ LITHIUS Pro DICE™ ramping steadily ▪ **POR**[*1] **advancing across multiple process steps in leading-edge logic/DRAM**
Etch	Sales Growth 25%+ YoY	▪ **Full-year sales of 1T yen** is within reach with accelerated investment in leading-edge logic/memory ▪ Evaluations progressing with new model for DRAM HARC etch
Advanced Packaging	Sales Growth **70%+** YoY	▪ In particular, our probers hold an overwhelming position in high-end logic. Expect to **significantly exceed 100B yen for full year.** Evaluations of new model progressing well

*1 POR (Process of Record): Certification of the adoption of equipment in customers' semiconductor production processes

Future Business Opportunities
(Highlights)

From POR to High Volume Manufacturing	▪ Cryogenic etch ▪ Low-resistivity metal deposition ▪ Hybrid bonding
Cumulative Sales through 2030	▪ DRAM interconnect etch: **1T yen** ▪ Bonding-related equipment: 500B yen
New Entrants/ SAM Expansion	▪ Single wafer PECVD for gap fill: 10% of PECVD market ▪ Device prober: 10-15% of prober market. **Released Prexa™ SDP**[*2]

*2 SDP: Singulated Device Prober

Financial Estimates for H1 FY2027

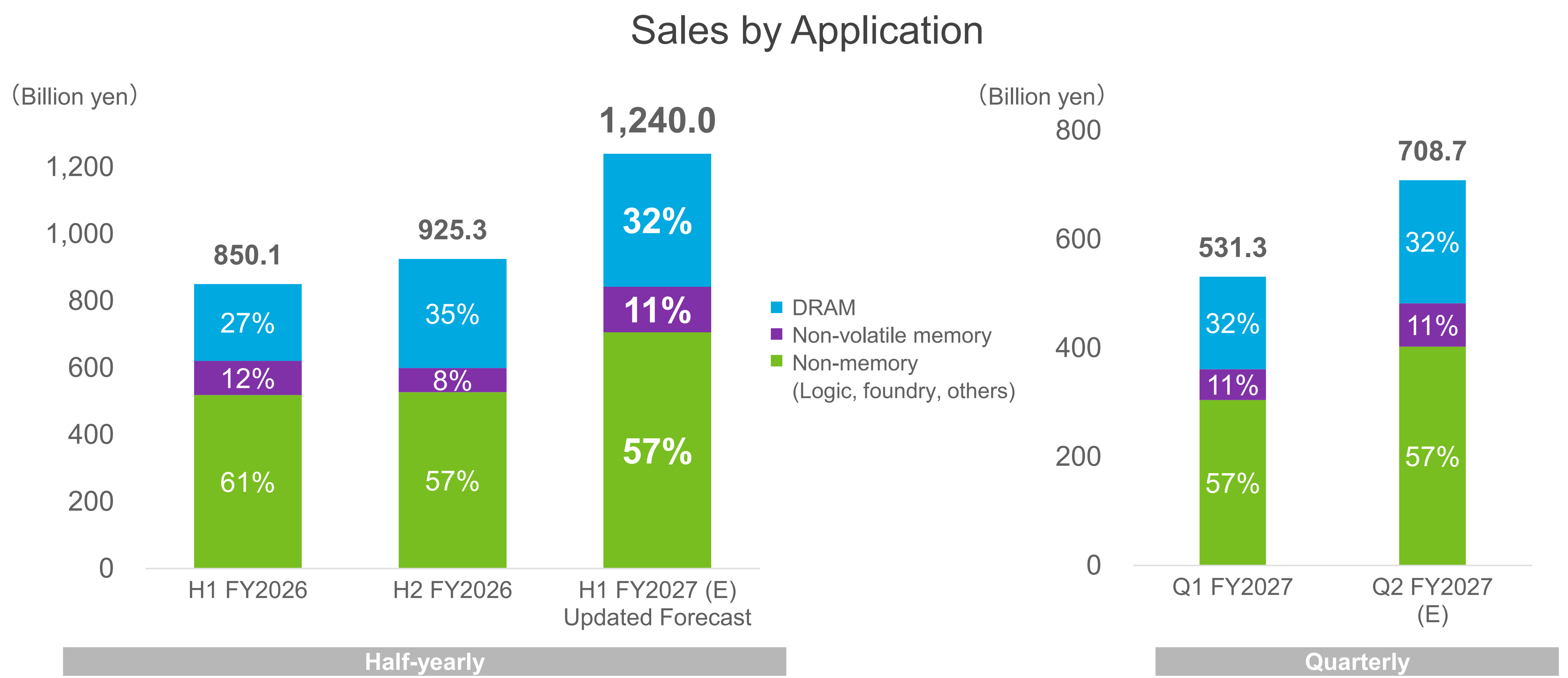
(Billion Yen)

	FY2026 (Actual)			FY2027 (Updated Forecast)	FY2027 (Forecast as of 4/30)
	H1	H2	Full Year	H1	H1
Net sales	1,179.6	1,263.8	2,443.5	**1,620.0**	1,570.0
Gross profit	538.8	569.0	1,107.8	**748.0**	715.0
Gross profit margin	45.7%	45.0%	45.3%	**46.2%**	45.5%
SG&A expenses	235.7	247.2	482.9	**290.0**	284.0
R&D	134.8	143.0	277.8	**160.0**	160.0
Other than R&D	100.8	104.1	205.0	**130.0**	124.0
Operating income	303.1	321.7	624.9	**458.0**	431.0
Operating margin	25.7%	25.5%	25.6%	**28.3%**	27.5%
Income before income taxes	312.9	435.1	748.1	**464.0**	437.0
Net income attributable to owners of parent	241.6	332.8	574.4	**349.0**	328.0
Net income per share (Yen)	527.31		1,254.57	**767.51**	721.12

- H1 FY2027:
  Revised net sales upward to 1,620B yen due to customers' robust investment in leading-edge applications

- H2 FY2027:
  Demand is expected to gain momentum further, raising expectations for a significantly better performance in H2
  - Closely monitoring the impact of the Middle East and supply chain developments

H1 FY2027 SPE New Equipment Sales Forecast

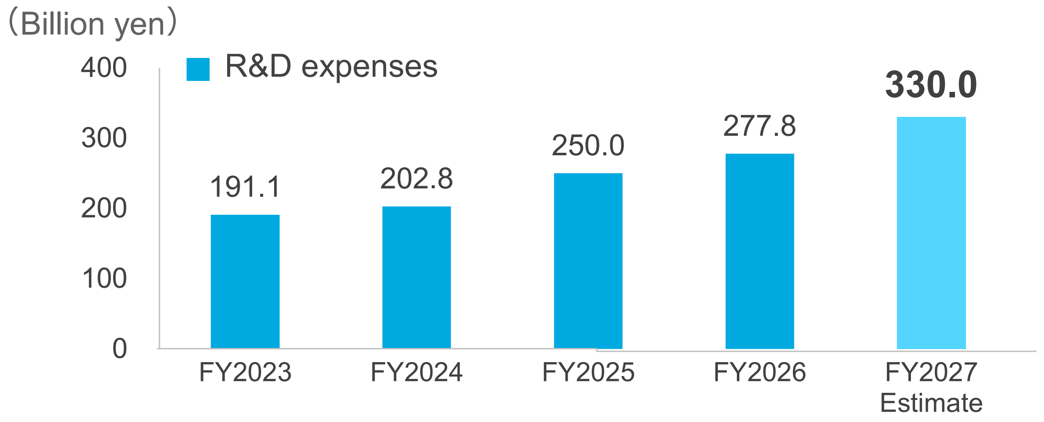


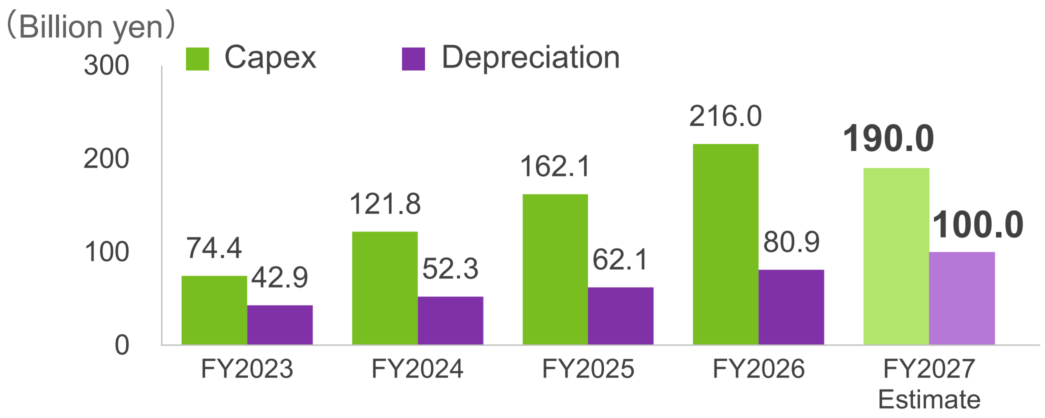
* Percentages on the graph show the composition ratio of new equipment sales. Field solutions sales are not included.

Revised New Equipment sales upward to 1,240B yen

Q2 anticipated to be new record high of 708.7B yen (+33% QoQ)

FY2027 R&D Expenses and Capex Plan





Miyagi Innovative Production Center

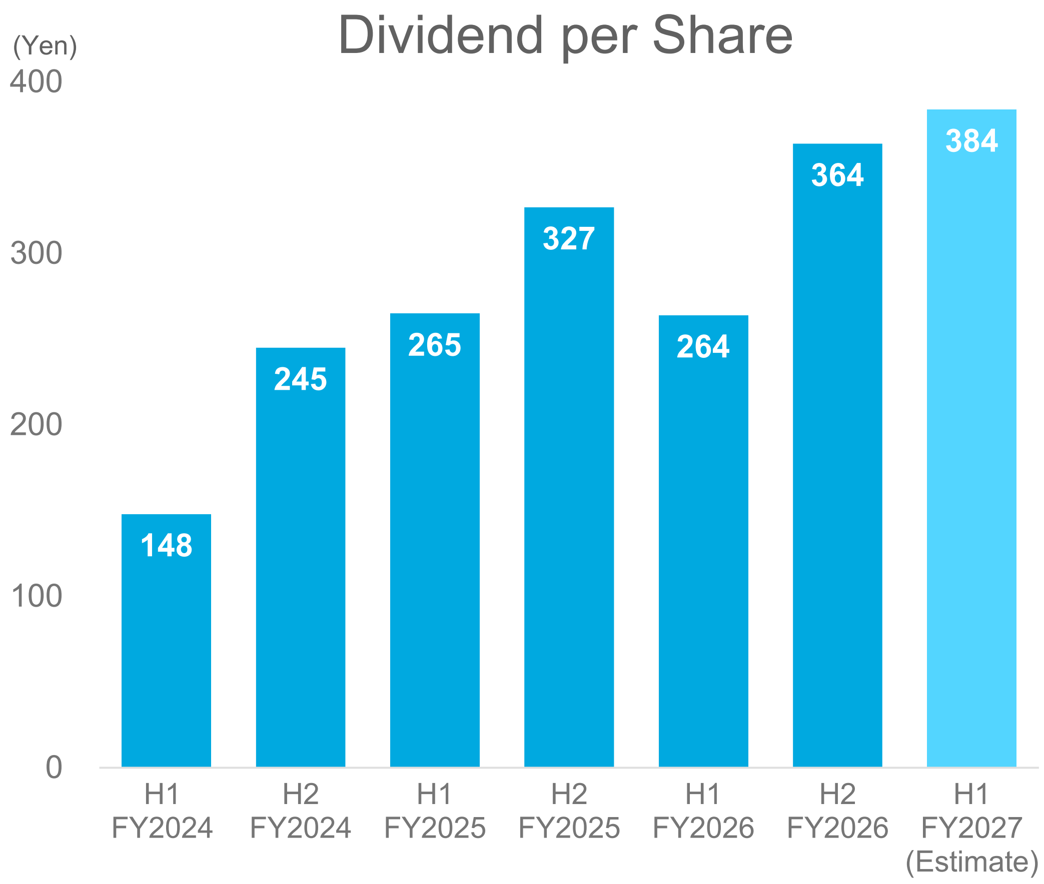
Kurokawa-gun, Miyagi Prefecture/ Completion scheduled for summer 2027

Goal of the Smart Production Concept

Labor Productivity	Space Efficiency
4x	3x
Production Leadtime	**Production Capacity**
1/3	3x

Continue strengthening competitiveness with a focus on R&D investment
Leveraging this solid infrastructure to steadily capture future gains

Dividend Forecast



TEL shareholder return policy

Dividend payout ratio: 50%

Annual DPS of not less than 50 yen

We will review our dividend policy if the company does not generate net income for two consecutive fiscal years

We will flexibly consider share buybacks

Dividend per share for H1 FY2027 (interim dividend) is updated to 384 yen

Acquisition of Treasury Stock

Implementing share repurchase of up to 150B yen

- Resolution of the Board of Directors' meeting held on May 29, 2026
  - Type of shares to be acquired: Shares of common stock
  - Total number of shares to be repurchased: Up to 7.5 million shares*
    (Equivalent to 1.6% of outstanding shares excluding treasury stock)
  - Total purchase amount for share repurchase: Up to 150 billion yen*
  - Period of repurchase: From June 1, 2026 to March 31, 2027

* Depending on market environment and other factors, it is possible that a share repurchase of only a portion of the above, will be carried out.

- Status of Share Repurchase as of June 30, 2026
  - Total number of shares repurchased: 207,100 shares
  - Total purchase amount for share repurchase: 11,474,246,000 yen

TEL will continue to manage our balance sheet appropriately, considering our ability to generate cash, necessary cash on hand and growth investment capital

Stock Split

■ Purpose	By implementing the stock split to lower the minimum investment, we intend to make shares more affordable for investors, with a view to expanding the investor base
■ Split Method	Each share of common stock owned by shareholders listed or recorded in the closing register of shareholders on the record date of Wednesday, September 30, 2026, will be split into 5 shares
■ Schedule	Date of public notice of record date: September 15, 2026 (Tuesday) Record date: September 30, 2026 (Wednesday) Effective date: October 1, 2026 (Thursday)
■ Dividends	As the effective date of the stock split is October 1, 2026, the interim dividends for the fiscal year ending March 2027, to all shareholders with a record date of September 30, 2026, will be implemented based on the number of shares issued prior to the stock split

Introducing Our New Organizational Structure

- Corporate Officers

Toshiki Kawai*1 President & CEO	Hiroshi Ishida*1 Senior Executive Vice President & COO
Shinichi Hayashi*1 *2 Development and Production	Keiichi Akiyama Product Business
Shingo Tada *2 Customer Strategy, Global Customer Engineering	Tatsuya Aso*2 Global Business Platform
Kazuhiro Doh *2 Corporate Strategy & Planning	

*1 Concurrently serves as TEL Corporate Director
*2 New Representative

- CxO under the New Organization (Highlights)

Toshiki Kawai, CEO

Hiroshi Ishida, COO

Hiroshi Kawamoto, CFO

TEL
TOKYO ELECTRON

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